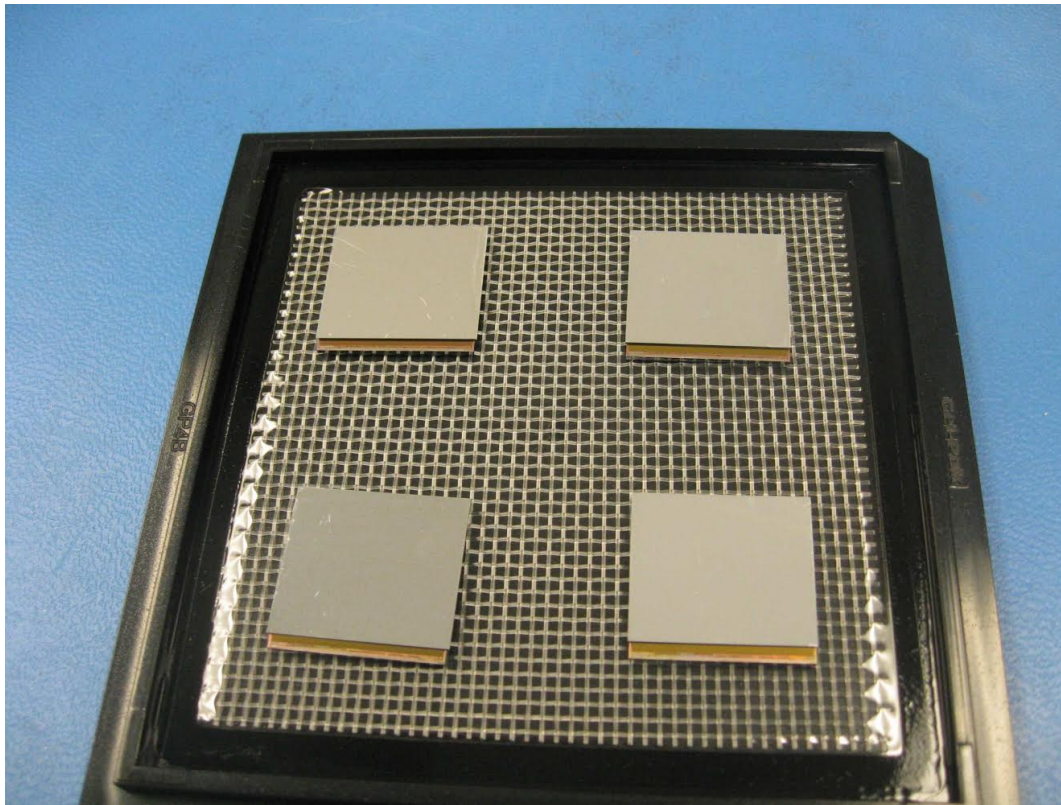


- This meeting: intended as a working group meeting for US institutes working on items related to pixel modules
- Meetings are announced via [usatlas-hllhc-pixel@cern.ch](mailto:usatlas-hllhc-pixel@cern.ch)
  - Please encourage your group members to sign up if they haven't already
- We hope to hear about your activities soon!
- US ATLAS pixel meeting on May 20<sup>th</sup> at 1 pm PT
  - Philippe has requested that we be prepared to discuss our group activities and plans
- Other news?
  - Test beam

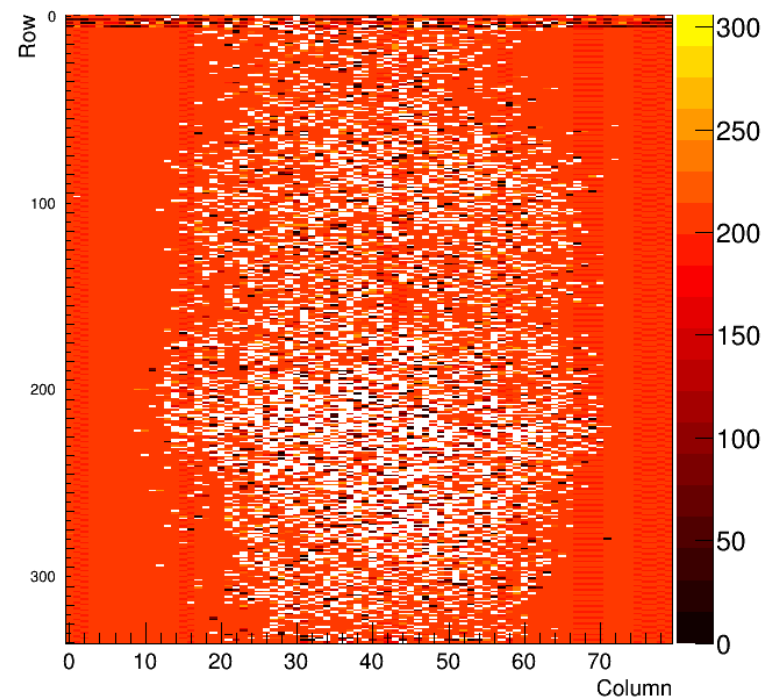
RTI modules arrived at SLAC!  
6 quads + 6 singles

From Chris Kenney, 4 single chip sensors:



- 3 single chip modules were loaded at LBNL
- Analog injection test indicates lots of shorted pixels
  - All 3 modules look qualitatively the same

Occupancy mod 0 bin 0 chip 0

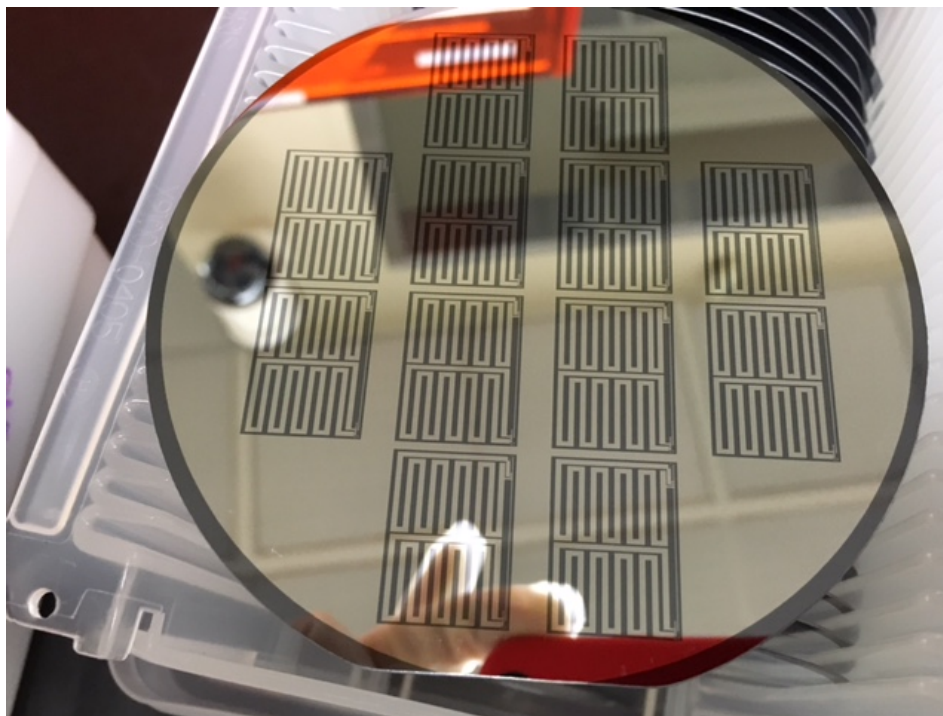


- RTI believes they missed a cleaning step
- Left a polymer film
- 2 non-mounted modules will be reworked
- Waiting for confirmation

Summarized from Chris Kenney:

“ASIC” wafer had metal deposited, lithography, and etching by Julie Segal (SLAC)

- 72/75 wafers were successful
- ‘snake’ resistance is about 20  $\Omega$  for oxide wafers, 30  $\Omega$  non-oxide wafers (8  $\Omega$  target)
- Wafers out for thinning as of last week
- Expect dicing soon
- Expect to complete in mid-May



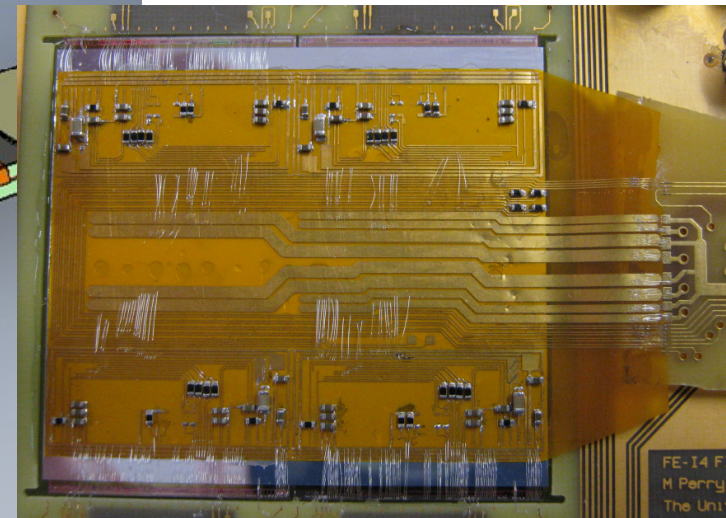
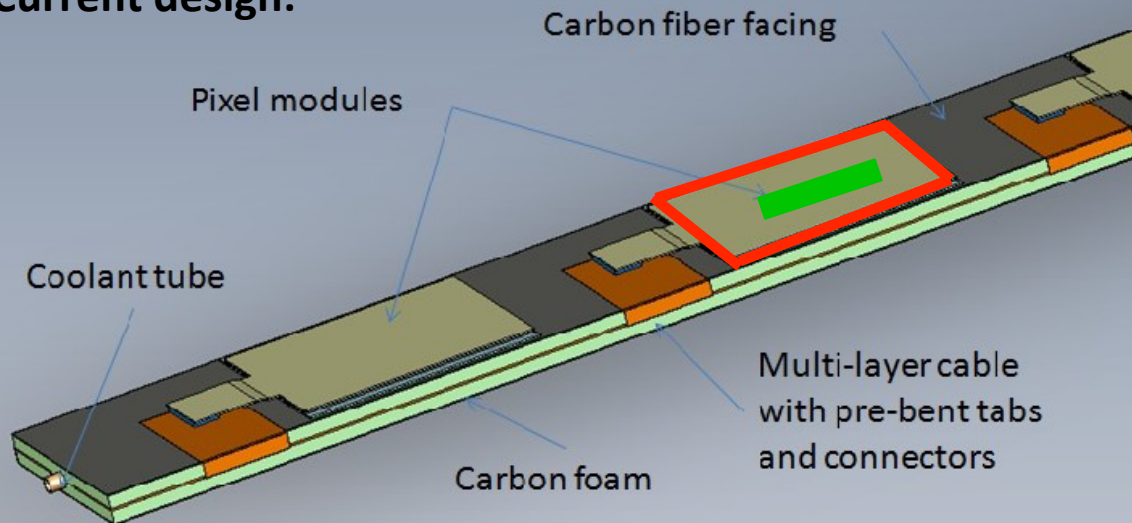


# Quad Module Flex Redesign

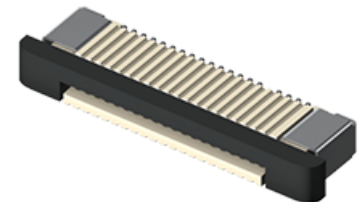
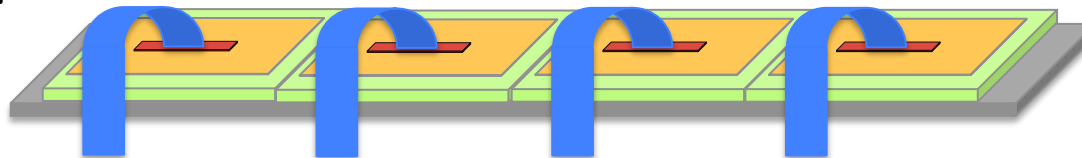
Argonne redesign the quad module flex cable:

- Add a connector on the quad module flex cable to allow modules to be placed adjacent to each other

## Current design:



## Updated concept:



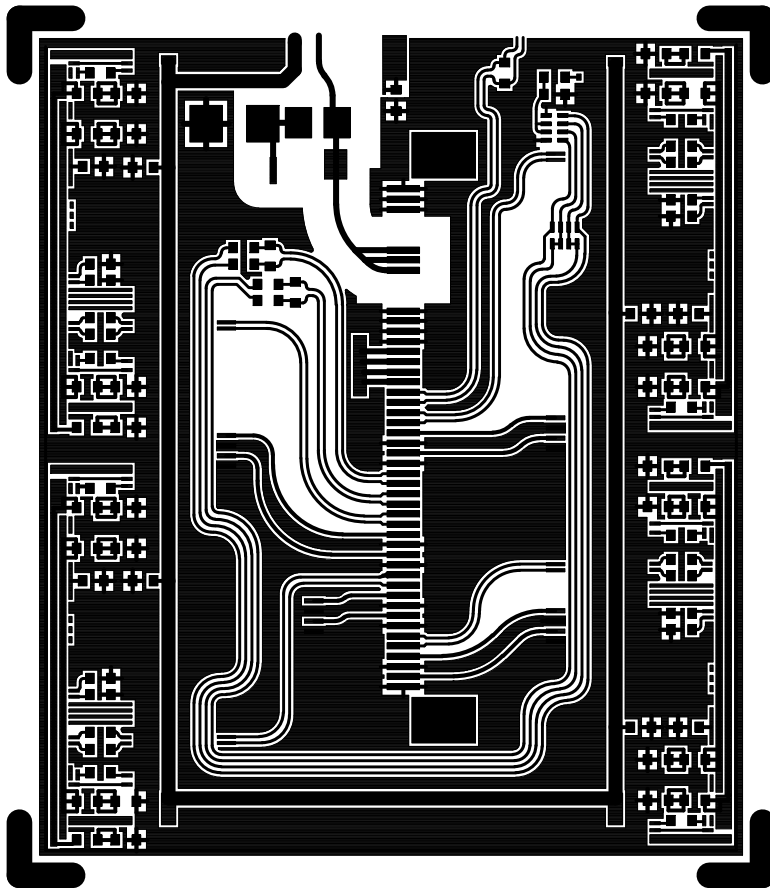
ZIF connector

# Quad Flex Cable

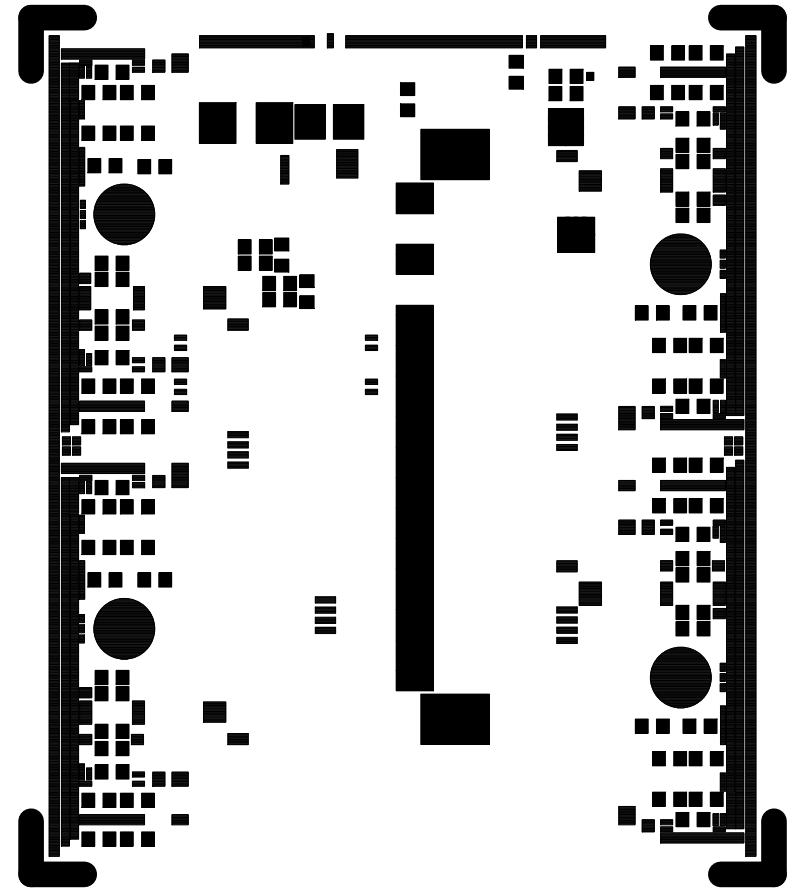
Redesign finished

- Please take a look offline to see if you notice any issues
- Files attached to meeting agenda

Top Copper



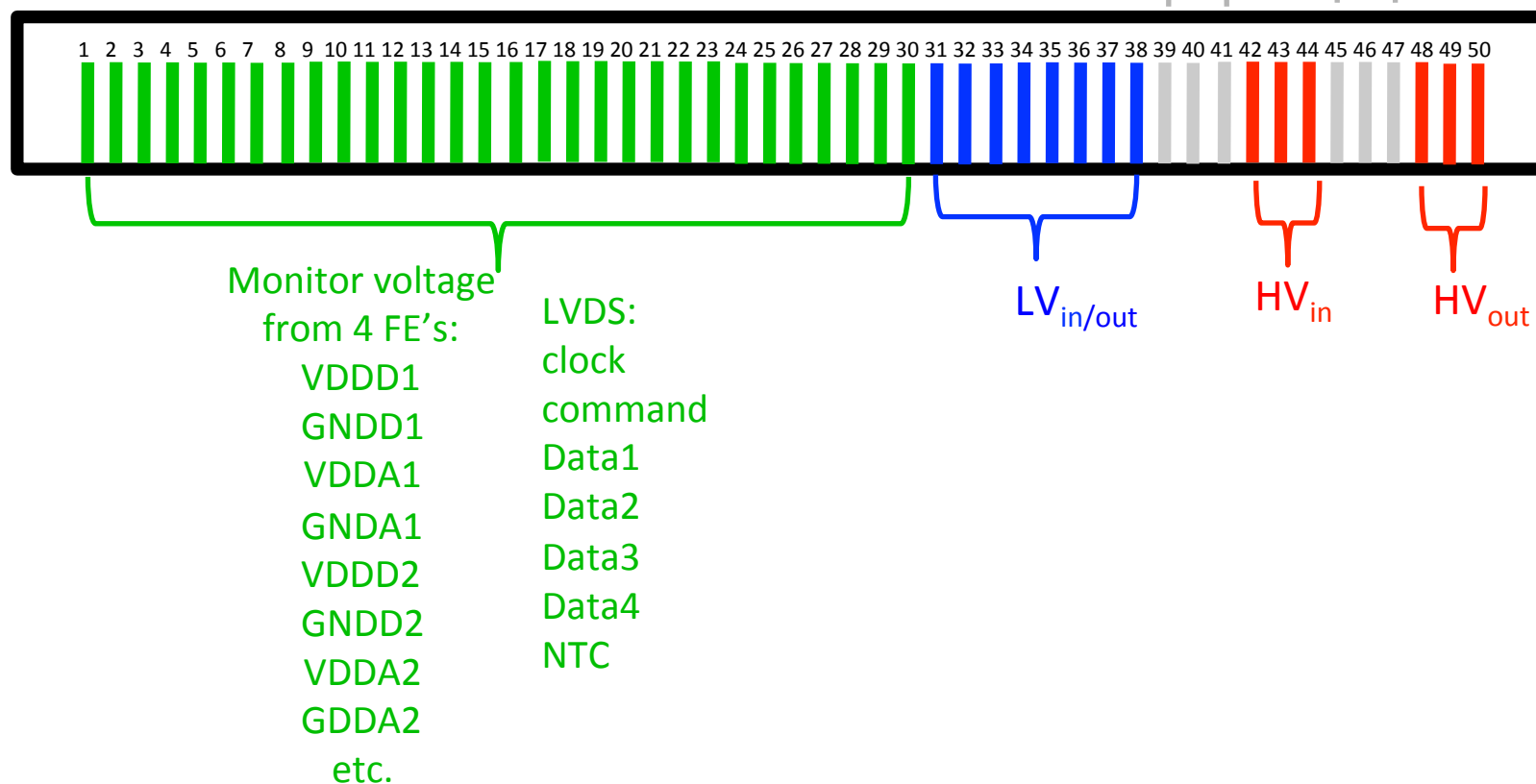
Top Overlay



# Quad Flex Pin-out

Current Layout:

Remove  
3 pins = 1.5 mm





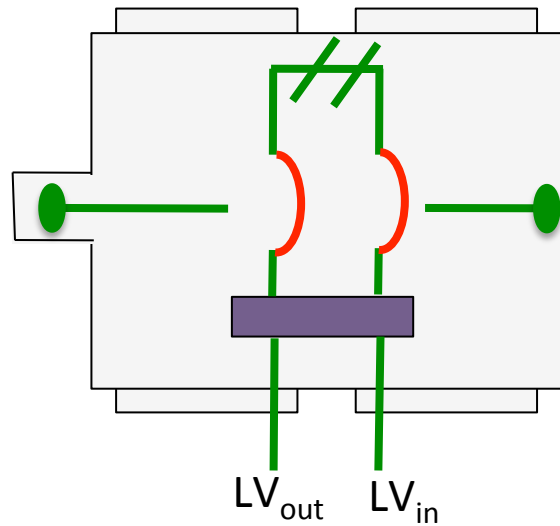
# Quad Flex Pin-out

Pin-out:	Pin		Pin	
	1	GNDA3	26	VDDD4
	2	VDDA3	27	Data4+
	3	GNDD3	28	Data4-
	4	VDDD3	29	NTC-
	5	Data3+	30	NTC+
	6	Data3-	31	LV_IN
	7	GNDA2	32	LV_IN
	8	VDDA2	33	LV_IN
	9	GNDD2	34	LV_IN
	10	VDDD2	35	LV_OUT
	11	Data2-	36	LV_OUT
	12	Data2+	37	LV_OUT
	13	GNDA1	38	LV_OUT
	14	VDDA1	39	-
	15	GNDD1	40	-
	16	VDDD1	41	-
	17	Data1-	42	HV_IN
	18	Data1+	43	HV_IN
	19	Command-	44	HV_IN
	20	Command+	45	-
	21	Clock-	46	-
	22	Clock+	47	-
	23	GNDA4	48	HV_OUT
	24	VDDA4	49	HV_OUT
	25	GNDD4	50	HV_OUT

Backup

# Daisy Chain

Single Module:



 = wire bond

Daisy Chain:

